Panasonic

Zener Diode

DZ2J027×0L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 2J or 2U

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C Parameter Symbol

Repetitive peak forward current	IFRM	200	mA
Total power dissipation ^{*1}	PT	200	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	Tj	150	С°
Operating ambient temperature	Topr	Topr -40 to +85	
Storage temperature	Tstg	-55 to +150	°C

 Note)
 *1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)

 Solder in (Recommended land pattern)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω, Contact discharge : 10 times)



Parameter	Symbol	Conditions		Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	2.57		2.84	V
Zener operating resistance	RZ	IZ = 5 mA			110	Ω
Reverse current	IR	VR = 1 V			120	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-1.9		mV/°C

Rating

Unit

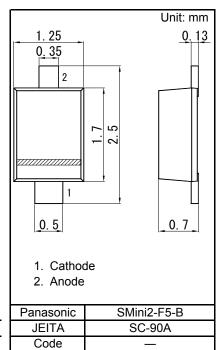
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

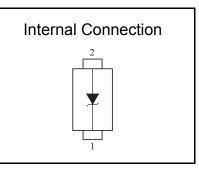
2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 $^{\circ}\text{C}$ for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 $^\circ\text{C}).$

*2	VZ guaranted 20 ms after current flow	Rank	c classification						
*3	Tj = 25 °C to 150 °C	-	Code	М		0	0		
		-	Rank M		No-rank				
		-	VZ	2.63	to	2.77	2.57	to	2.84
		-	Marking symbol	2U		2J			
		-							

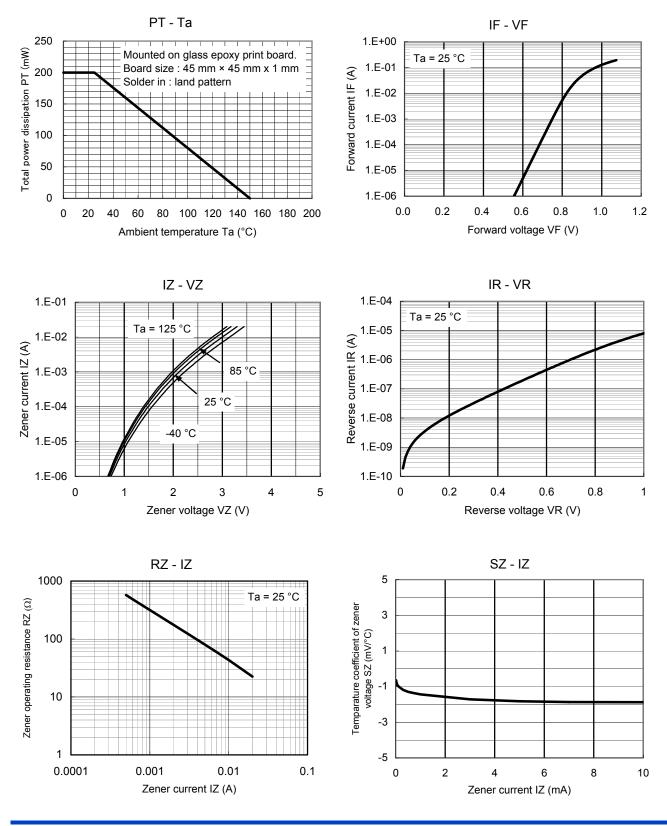






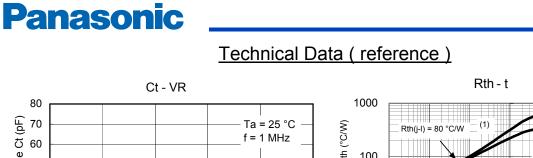
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Technical Data (reference)



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Terminal capacitance Ct (pF) Thermal resistance Rth (°C/W) (2) 100 50 40 30 10 (1) Non-heat sink 20 (2) Mounted on glass epoxy print board. Board size : 45 mm × 45 mm x 1 mm Solder in : land pattern 10 1 0 0 0.2 0.4 0.6 0.8 1 0.001 0.01 0.1 1 10 Reverse voltage VR (V) Time t (s) PZSM - tw 100 Non-repetitive reverse surge power dissipation PZSM (W) Ta = 25 °C 10 1

10000

Zener Diode

DZ2J027×0L

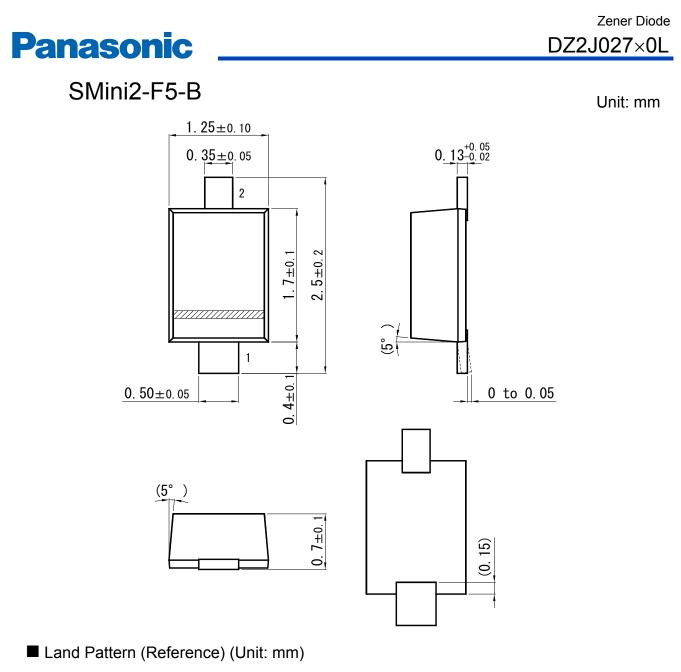
100

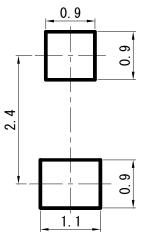
1000

0.1 100

1000

Pulse width tw (µs)





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